

MA2DF60

Silicon Mesa type

For high frequency rectification

■ Features

- High switching speed t_{rr}
- Soft recovery

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	600	V
Non-repetitive peak reverse surge voltage	V_{RSM}	600	V
Forward current	I_F	5	A
Non-repetitive peak forward surge current *	I_{FSM}	40	A
Junction temperature	T_j	-40 to +150	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$

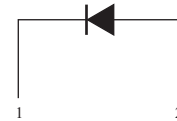
Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Package

- Code
TO-220D-B1
- Pin Name
1: Cathode
2: Anode

■ Marking Symbol: MA2DF60

■ Internal Connection



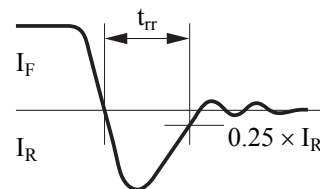
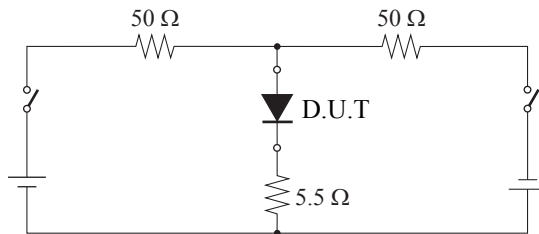
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 5 \text{ mA}$		1.4	1.7	V
Reverse current	I_{RRM}	$V_{RRM} = 600 \text{ V}$			30	μA
Reverse recovery time *	t_{rr}	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}$ $I_{rr} = 0.25 \text{ A}$		15	25	ns
Thermal resistance (j-a)	$R_{th(j-a)}$				3.0	$^\circ\text{C/W}$
Thermal resistance (j-c)	$R_{th(j-c)}$				63	$^\circ\text{C/W}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

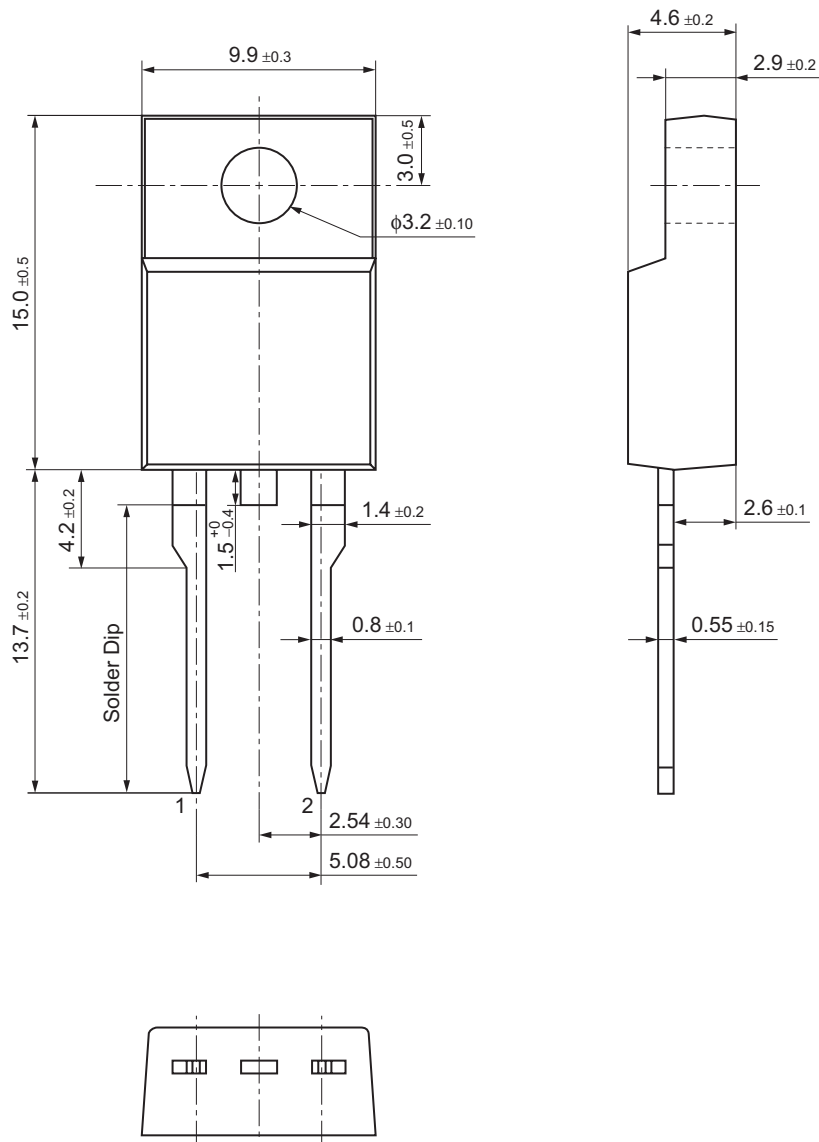
2. Absolute frequency of input and output is 10 MHz.

3. *: t_{rr} measurement circuit



TO-220D-B1

Unit: mm



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